



S/N 09/897,320

PATENT

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10-11
Robert

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh

Examiner: Gregory Thompson

Serial No.: 09/897,320

Group Art Unit: 2835

Filed: June 29, 2001

Docket: 884.462US1

Title:

ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND METHODS OF MANUFACTURE (as amended)

AMENDMENT AND RESPONSE UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on June 17, 2002. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from September 17, 2002 to October 17, 2002.

IN THE TITLE

Please change the title to the following:

ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND METHODS OF MANUFACTURE

IN THE SPECIFICATION

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs:

The paragraph beginning at page 1, line 6, is amended as follows:

Embodiments of this invention relate [This invention relates] generally to printed circuit boards and components coupled thereto [therewith,] and, in particular, [relates] to an electronic assembly with solderable heat sinks and methods of manufacturing [components that are to be joined with the printed circuit board].